

Title (en)

Gold alloys and master alloys for obtaining them

Title (de)

Goldlegierungen und Vorlegierungen zu deren Herstellung

Title (fr)

Alliages d'or et alliages-mères pour leur obtention

Publication

**EP 1266974 A1 20021218 (EN)**

Application

**EP 01830349 A 20010530**

Priority

EP 01830349 A 20010530

Abstract (en)

Gold alloy comprising, by weight, at least Gold Au  $\geq 51$  %, Iridium Ir  $\leq 0.1$  %, Germanium Ge  $\leq 2$  % and Copper Cu  $\leq 45$  %. The alloy can also comprise, in percentage by weight, Silver Ag  $\leq 34$  %, nickel Ni  $\leq 20$  % and Zinc Zn  $\leq 12$  %. In some variations the gold alloy can further comprise no more than 4% of at least one of the elements of the group constituted by cobalt, manganese, tin and indium, and no more than 0.15% of at least one of the deoxidising elements of the group constituted by magnesium, silicon, boron and lithium. To the alloy can also be added at least one of the refining elements of the group constituted by ruthenium, rhenium and platinum in quantities not exceeding 0.4% by weight. The invention further relates to a master alloy for obtaining said gold alloy. <IMAGE>

IPC 1-7

**C22C 9/05**

IPC 8 full level

**C22C 1/03** (2006.01); **C22C 5/02** (2006.01)

CPC (source: EP US)

**C22C 1/03** (2013.01 - EP US); **C22C 5/02** (2013.01 - EP US)

Citation (search report)

- [X] EP 0381994 A1 19900816 - HAFNER C GMBH & CO [DE]
- [X] DE 4320928 C1 19940317 - HERAEUS KULZER GMBH [DE]
- [X] DE 3019277 A1 19811126 - WIELAND FA DR TH [DE]
- [X] PATENT ABSTRACTS OF JAPAN vol. 012, no. 444 (C - 545) 22 November 1988 (1988-11-22)
- [X] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 12 25 December 1997 (1997-12-25)
- [X] PATENT ABSTRACTS OF JAPAN vol. 1999, no. 04 30 April 1999 (1999-04-30)
- [X] PATENT ABSTRACTS OF JAPAN vol. 1995, no. 02 31 March 1995 (1995-03-31)

Cited by

WO2014108849A1; GB2418432A; ITPD20130002A1; RU2626260C1; ITPD20130003A1; CN104903477A; RU2476615C1; RU2652900C1; WO2015193659A3; WO2016084038A3; WO2022180650A1; WO2007083169A1; WO2014108848A1

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

**EP 1266974 A1 20021218; EP 1266974 B1 20040929**; AT E278045 T1 20041015; DE 60105987 D1 20041104; ES 2227106 T3 20050401; US 2003012679 A1 20030116

DOCDB simple family (application)

**EP 01830349 A 20010530**; AT 01830349 T 20010530; DE 60105987 T 20010530; ES 01830349 T 20010530; US 15638602 A 20020529